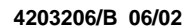


## METAL SINGLE-IN-LINE MODULE



- NOTES:
- |  |   |
|--|---|
| A. All linear dimensions are in inches (mm).   | G. Vias are recommended to improve copper adhesion.   |
| B. This drawing is subject to change without notice.                                       | H. Solder mask openings to copper island for solder joints to mechanical pins. Electrically connect case to ground plane. |
| C. 2 place decimals are $\pm 0.030$ ( $\pm 0,76$ mm).                                      | I. Case outline reference.  |
| D. 3 place decimals are $\pm 0.010$ ( $\pm 0,25$ mm).                                      |   |
| E. Recommended mechanical keep-out area.   |   |
| F. Power pin connections should utilize two or more vias per input, ground and output pin. |   |

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